

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listings of Claims:

Claims 1-6 (Cancelled)

7. (original) A semiconductor device having a semiconductor chip mounted over a substrate in which an interconnect is formed, by using an adhesive layer to connect a stud bump of the semiconductor chip to one end of the interconnect and an external terminal of the semiconductor device to the other end of the interconnect,

wherein a common interconnect is disposed along the periphery of the substrate and the number of the stud bump to be connected to the common interconnect is greater than that of the external terminal to be connected to the common interconnect.

Claim 8 (Cancelled).

9. (Currently Amended) A semiconductor device according to Claim 8, having a semiconductor chip mounted over a substrate in which an interconnect is formed, by

using an adhesive layer to connect a stud bump of the semiconductor chip to one end of the interconnect and an external terminal of the semiconductor device to the other end of the interconnect,

wherein a bump electrode which will be an external terminal is formed, via a pad, at the other end of the interconnect, and wherein the pad is formed to have a substantially equal thickness to that of a base of the substrate.

Claims 10-15 (canceled).